

8/21/02

Docket Number: 96-0841.01

Paper No.: 10

Art Unit: 2815

Examiner: Brock II, P.

**For: DEVICE ISOLATION FOR
SEMICONDUCTOR DEVICES**

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Certificate of Mailing (37 C.F.R. §1.8)

20231, on the date below: 7/29/02 Tara Suelton
Date Signature

Dear Commissioner:

REPLY AND AMENDMENT UNDER 37 CFR §1.116

This paper is in response to outstanding Office Action dated 05/02/2002 and designated as paper no. 9.

In the Claims:

Please amend claims 25, 30, 31, 34, 37, 38, 40, 50, 53 and 54 as recited below.

25. (Twice Amended) A process for forming device isolation for a semiconductor assembly, said process comprising the steps of:

forming a first trench into a semiconductor substrate;